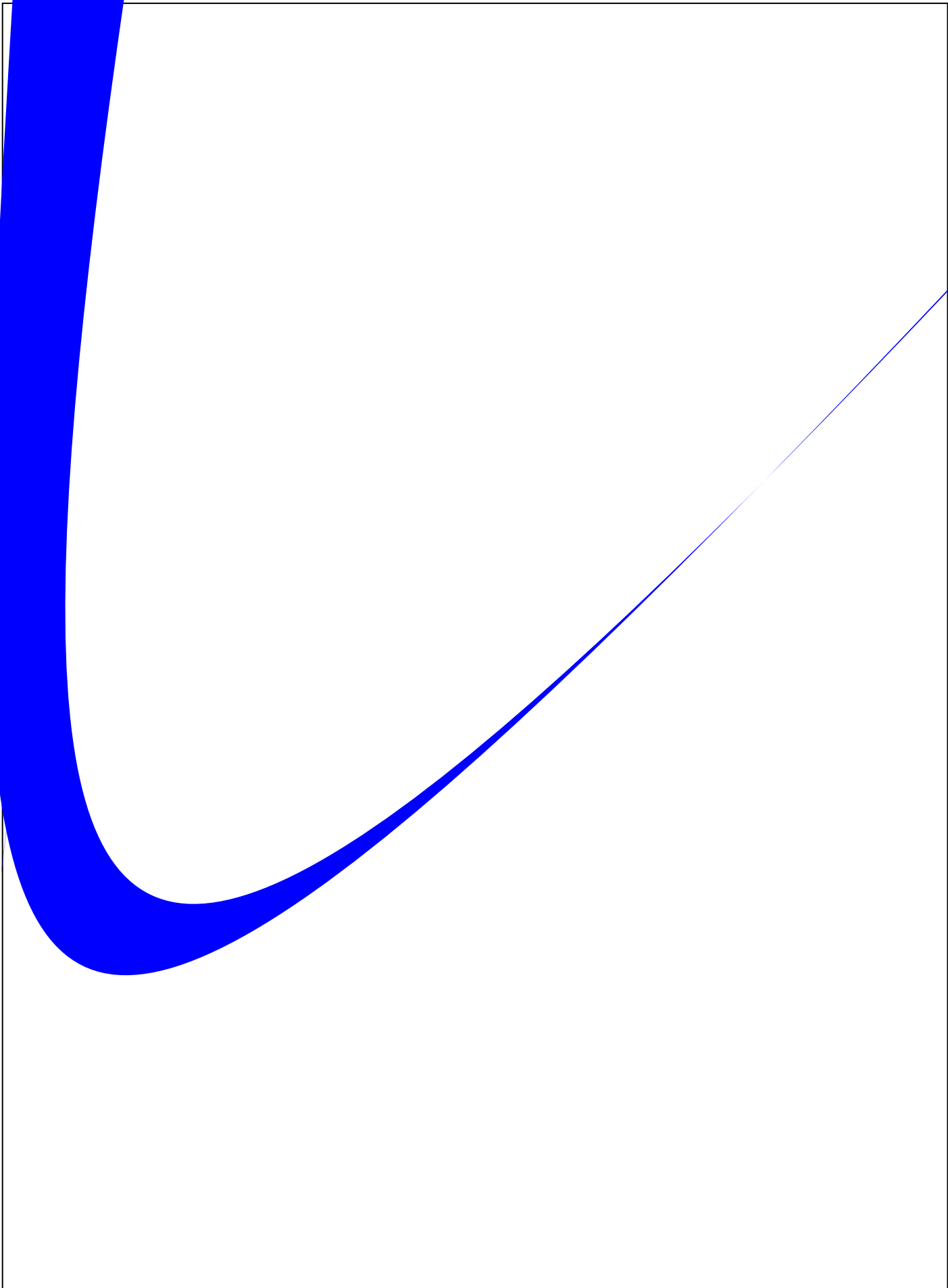
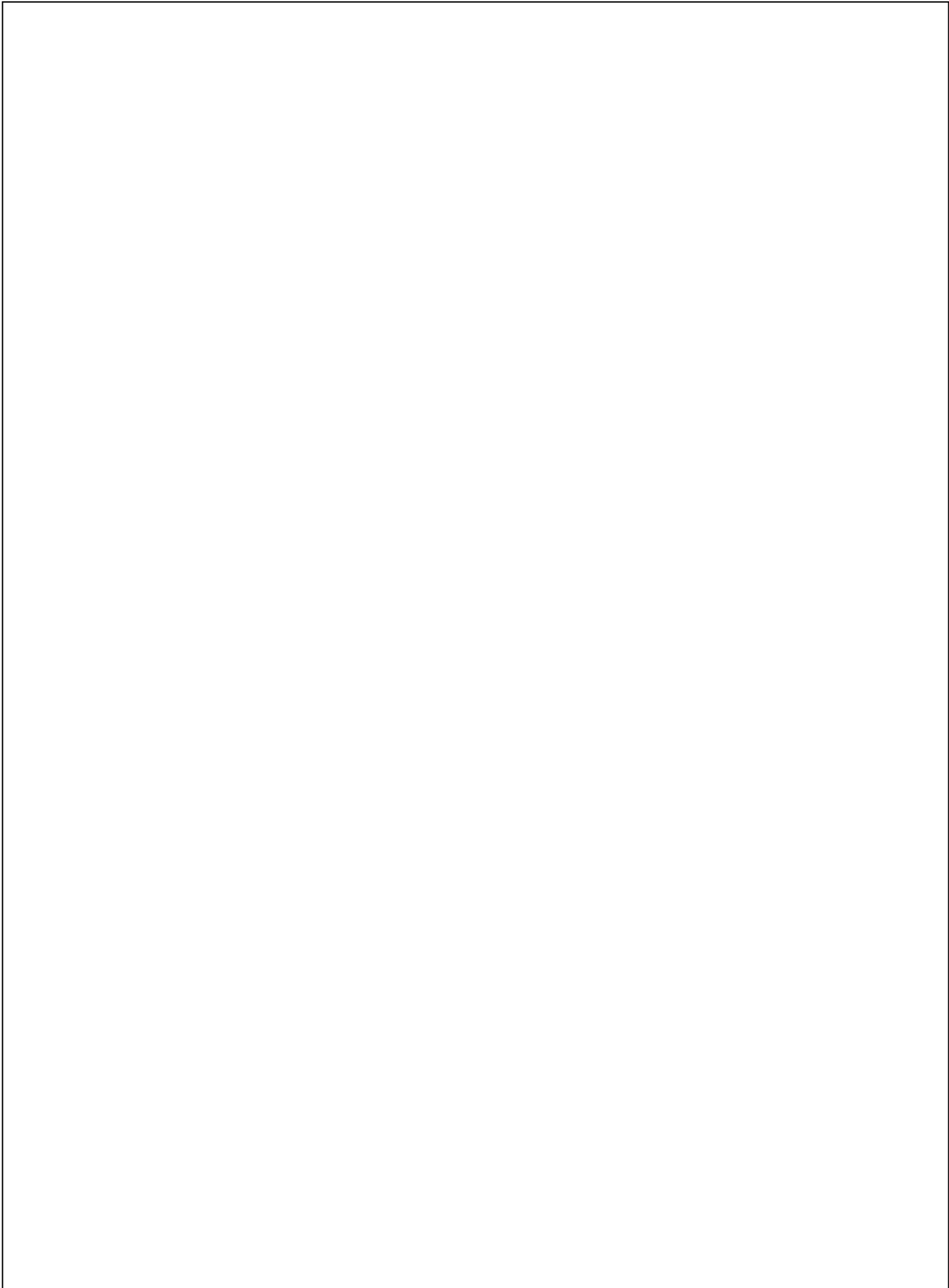


**LIGHT**







## Electrical Optical Characteristics at Ta=25°C

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Condition
Radiant Intensity	I <sub>e</sub>	2.2	3.0	4.4	mW/sr	I <sub>F</sub> =20mA (Note 1,3)
Viewing Angle	$\frac{1}{2}$	---	130	---	Deg.	(Note 2)
Peak Wavelength		---	940	---	nm	I <sub>F</sub> =20mA
Spectral Line Half- Width		---	50	---	nm	I <sub>F</sub> =20mA
Forward Voltage	V <sub>F</sub>	---	1.25	1.60	V	I <sub>F</sub> =50mA
Reverse Current	I <sub>R</sub>	---	---	100	μA	V <sub>R</sub> =5V

### Note:

1. Point sources of the amount of radiation per unit time in a given direction within the unit solid Angle radiated energy.
2.  $\frac{1}{2}$  is the off-axis angle at which the Radiant Intensity is half the axial Radiant Intensity.
3. The I<sub>e</sub> guarantee should be added ±15% tolerance.

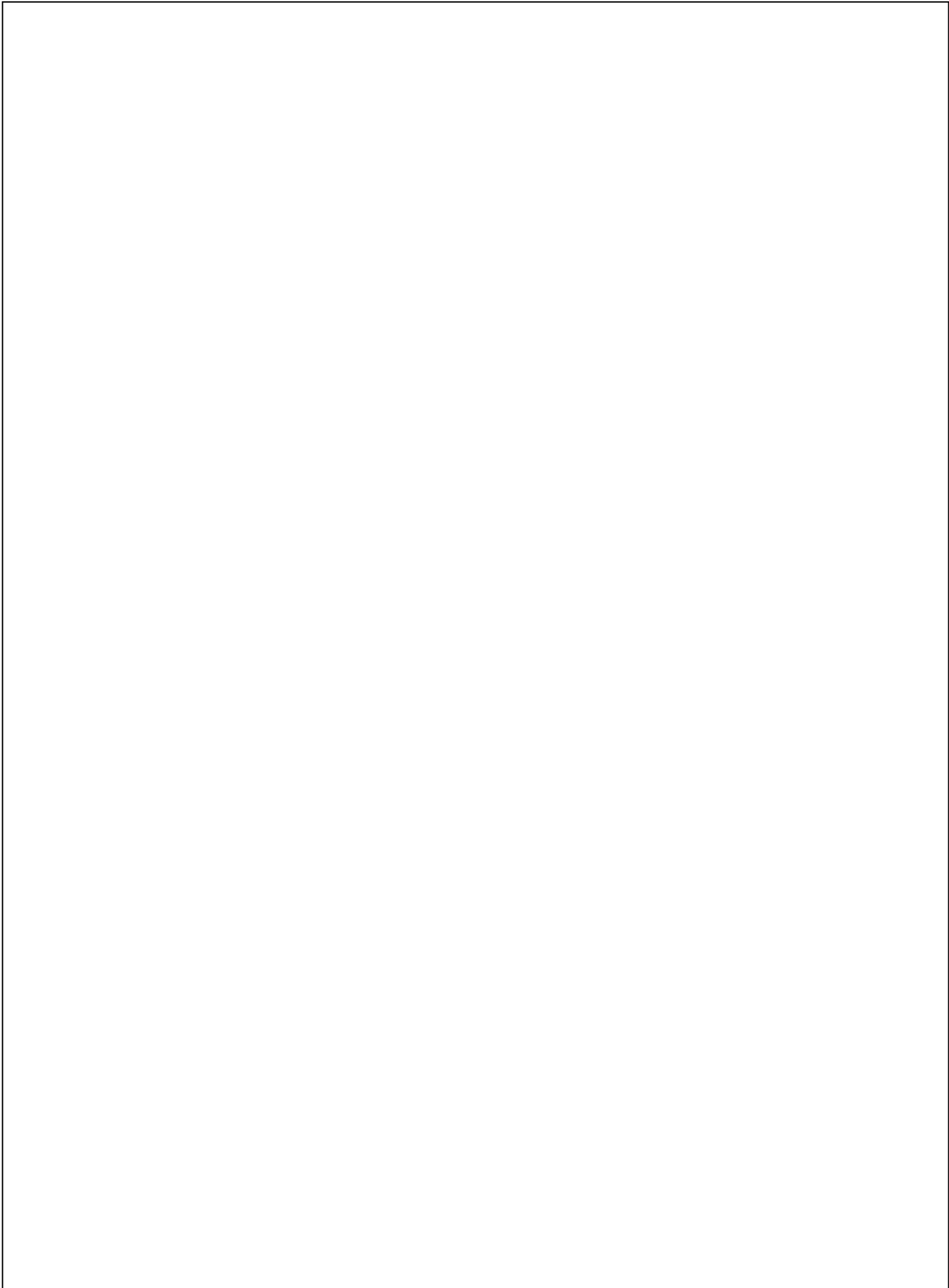
## Infrared Emitting Diode Specification

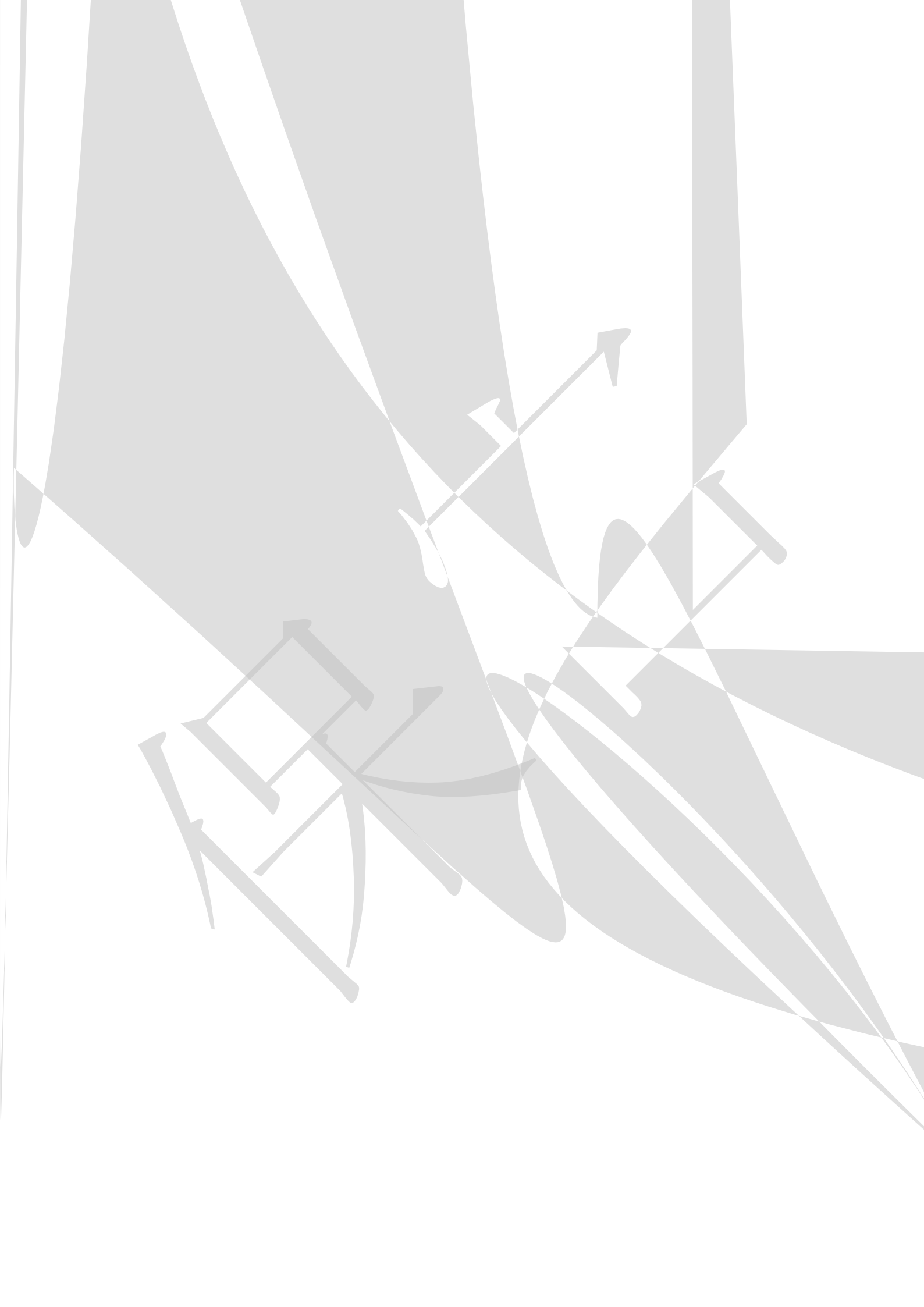
### ●Commodity: Infrared emitting diode

### ●Intensity Bin Limits (At 20mA)

BIN CODE	Min. (mW/sr)	Max. (mW/sr)
18	2.2	2.6
19	2.6	3.1
20	3.1	3.7
21	3.7	4.4

NOTE: The I<sub>e</sub> guarantee should be added ±15% tolerance.





## LED MOUNTING METHOD

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures (Fig.1).



